

Title (en)
PROCESS AND DEVICE FOR CONNECTING A PROBE TO A PRINTED CIRCUIT BOARD BY MEANS OF A PLUG CONNECTOR WITH TWO HALF-SHELLS

Title (de)
VERFAHREN UND VORRICHTUNG ZUM VERBINDEN EINER SONDE MIT LEITERPLATTE MIT EINEM AUS ZWEI HALBSCHALEN BESTEHENDEN VERBINDUNGSSTECKER

Title (fr)
PROCEDE ET DISPOSITIF POUR RELIER UNE SONDE A UNE CARTE DE CIRCUITS A L'AIDE D'UNE FICHE DE CONNEXION COMPOSEE DE DEUX SEMI-COQUES

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Application
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Abstract (en)
[origin: WO9967856A1] A process is disclosed for connecting a probe having electrical connections that end on a printed circuit board that can be inserted into a receptacle of a plug connector composed of two half-shells which carry on their mutually facing sides matching contacts for the connections of the printed circuit board, form an intermediate receptacle for the printed circuit board and are kept together by the pressure of a U-shaped spring that encloses them. The connection can be substantially simplified, without any risk of damage to the parts, in that the plug connector is inserted between two adjustable jaws and positioned in such a way that spreading projections of the adjustable jaws are aligned with the opening of the spring, the spring is spread apart over a predetermined path of displacement by displacing in opposite directions the spreading projections inserted into the opening of the spring, the printed circuit board is inserted into the thus widened receptacle between the half-shells and then retained between the half-shells of the plug connector by the pressure of the released spring after the spreading projections are set back and/or retracted.

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